

Patent Abstracts of Japan

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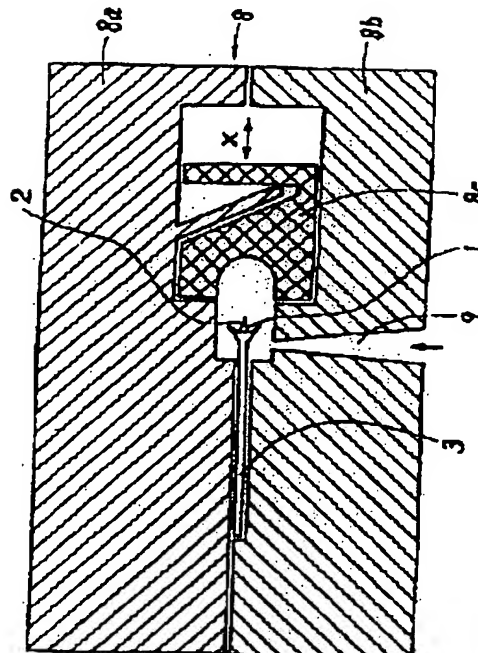
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TITLE : LIGHT EMITTING DEVICE



ABSTRACT : PURPOSE: To omit a flash removing step and to reduce a cost of a mold by injection molding thermoplastic resin having low thermal expansion coefficient at the time of molding sealing resin.

CONSTITUTION: A light emitting diode 1 is die bonded to a lead frame 3 via conductive paste, and then internally wired with bonding wires 2. Then, permeable thermoplastic polyimide resin is injected from an inlet 9 in a state that the frame is inserted to a mold 8; and resin-sealed. In this case, since the injection molding is executed by using the thermoplastic resin, a molding cycle until the resin is cured is shortened to 10-30sec. Accordingly, even in the case of the mold for injecting a small number can obtain a sufficient mass productivity. Sealing resin 4, i.e., a lens 4 is injection molded in a high viscosity state by using permeable thermoplastic polyimide resin having a low linear expansion coefficient, high melting viscosity.

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